

VMDSEMI

VUDE002R070NA

Datasheet

General Description

$V_{(BR)DSS}$	$R_{DS(ON)_{max}}$	I_D
20V	7.0mΩ@4.5V	25A
	7.5mΩ@4.0V	
	8mΩ@3.8V	
	9mΩ@3.1V	
	10mΩ@2.5V	

Symbol

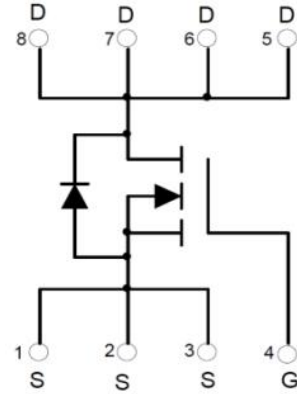


Figure 1 Symbol of VUDE002R070NA

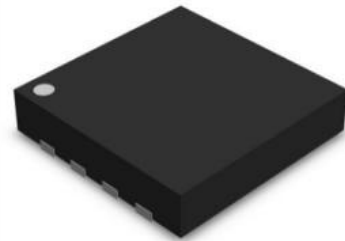
Features

- Low Gate Charge
- Low Gate Resistance
- Advanced high cell density Trench technology

Application

- Load / Power Switch
- Battery protection applications

Package Type



DFN3030-8L

Figure 2 Package Type of VUDE002R070NA

Ordering Information

Product Name	Package
VUDE002R070NA	DFN3030-8L

Absolute Maximum Ratings ($T_A = 25\text{ °C}$, unless otherwise specified)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DSS}	20	V
Gate-Source Voltage	V_{GSS}	± 12	V
Continuous Drain Current ^{Note1}	I_D	25	A
Pulsed Drain Current ^{Note2}	I_{DM}	75	A
Total Power Dissipation ^{Note3}	P_D	3	W
Junction Temperature	T_J	150	°C
Storage Temperature	T_{STG}	-55 to 150	°C

Thermal Resistance

Parameter	Symbol	Min	Typ	Max	Unit
Thermal Resistance, Junction-to-Ambient ^{Note1}	$R_{\theta JA}$		42		°C/W

Electrical Characteristics (T_A= 25 °C, unless otherwise specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Statistic Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V, I _D = 250uA	20			V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 16V, V _{GS} =0V			1	uA
Gate-Body Leakage Current	I _{GSS}	V _{GS} = ±12V, V _{DS} = 0V			±100	nA
Gate Threshold Voltage ^{Note4}	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250uA	0.4	0.7	1.0	V
Static Drain-Source On-Resistance ^{Note4}	R _{DS(on)}	V _{GS} =4.5V, I _D = 10A		5.5	7.0	mΩ
		V _{GS} =4.0V, I _D = 10A		6.0	7.5	
		V _{GS} =3.8V, I _D = 10A		6.5	8.0	
		V _{GS} =3.1V, I _D = 10A		7.0	9.0	
		V _{GS} = 2.5V, I _D = 10A		7.5	10.0	
Dynamic Characteristics						
Input Capacitance	C _{ISS}	V _{DS} =10V		1500		pF
Output Capacitance	C _{OSS}	V _{GS} =0V		260		pF
Reverse Transfer Capacitance	C _{RSS}	f=1MHz		240		pF
Total Gate Charge	Q _g	V _{DS} =10V		20		nC
Gate-Source Charge	Q _{gs}	V _{GS} =4.5V		4		
Gate-Drain Charge	Q _{gd}	I _D = 8A		9		
Switching Parameters						
Turn-on Delay Time	t _{d(on)}	V _{DD} = 10V		5		ns
Turn-on Rise Time	t _r	V _{GS} = 4.5V		15		
Turn-off Delay Time	t _{d(off)}	R _L =1.2Ω		70		
Turn-off Fall Time	t _f	R _{GEN} =3Ω		22		
Diode Characteristics						
Diode Forward Voltage ^{Note4}	V _{SD}	V _{GS} =0V, I _S = 10A T _J = 25 °C			1.2	V
Continuous Source Current	I _S	V _G =V _D =0V			25	A
Pulsed Source Current	I _{SM}	Force Current			75	

Notes :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper
- 2.Pulse Test:Pulse Width < 10us, Duty Cycle < 0.5%.
- 3.The power dissipation is limited by 150°C junction temperature
- 4.Pulse Test : Pulse width≤300μs, duty cycle≤0.5%.

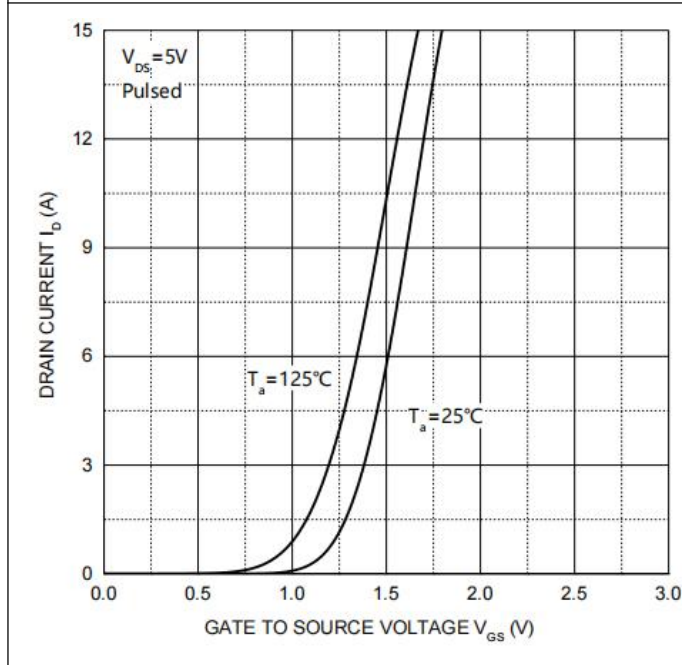
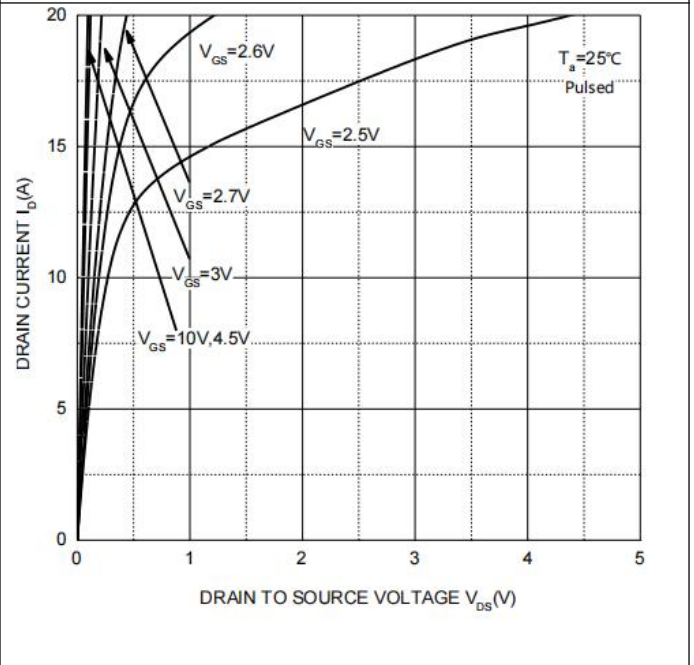
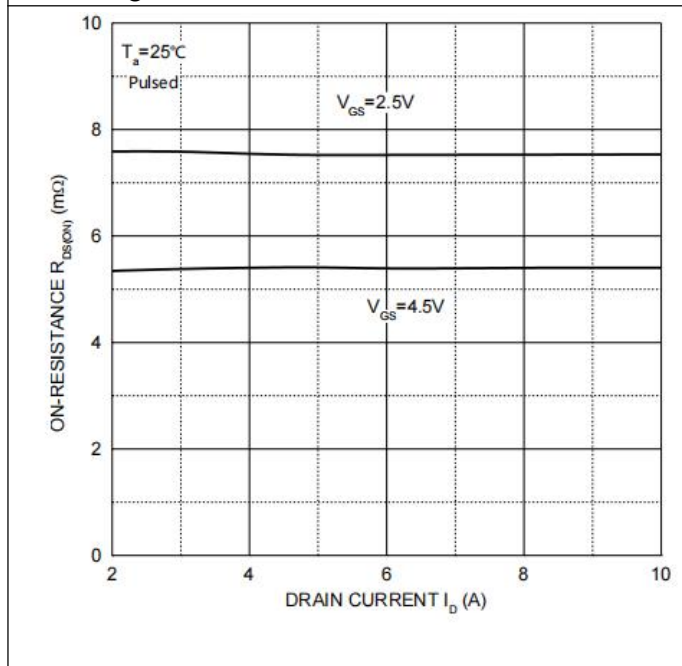
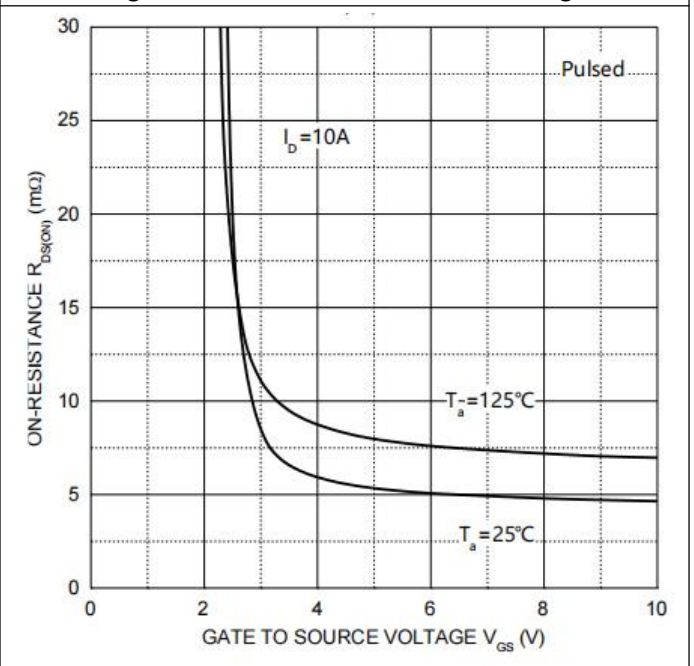
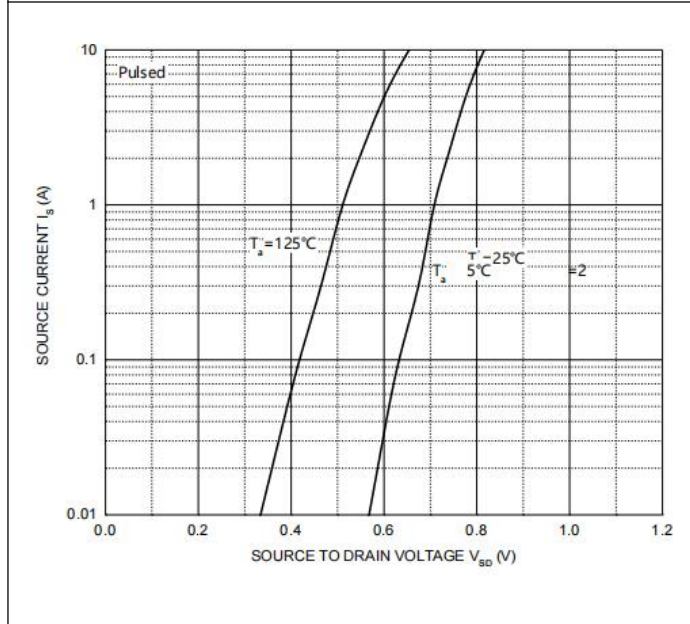
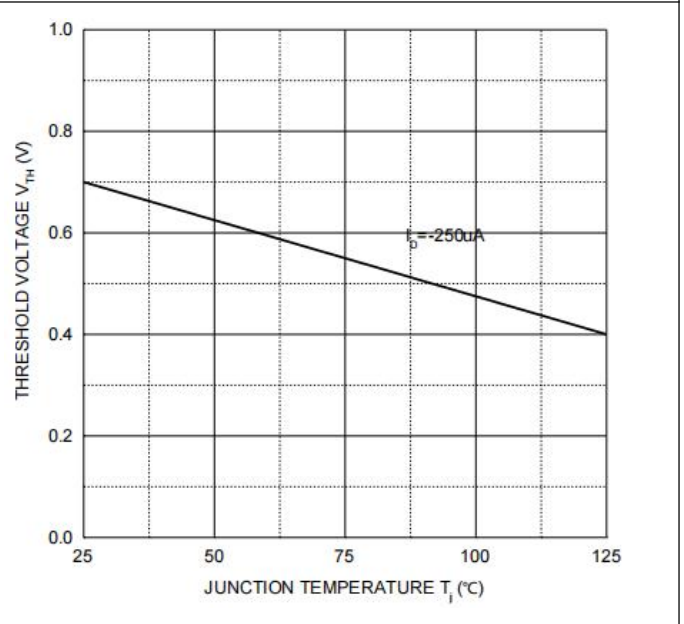
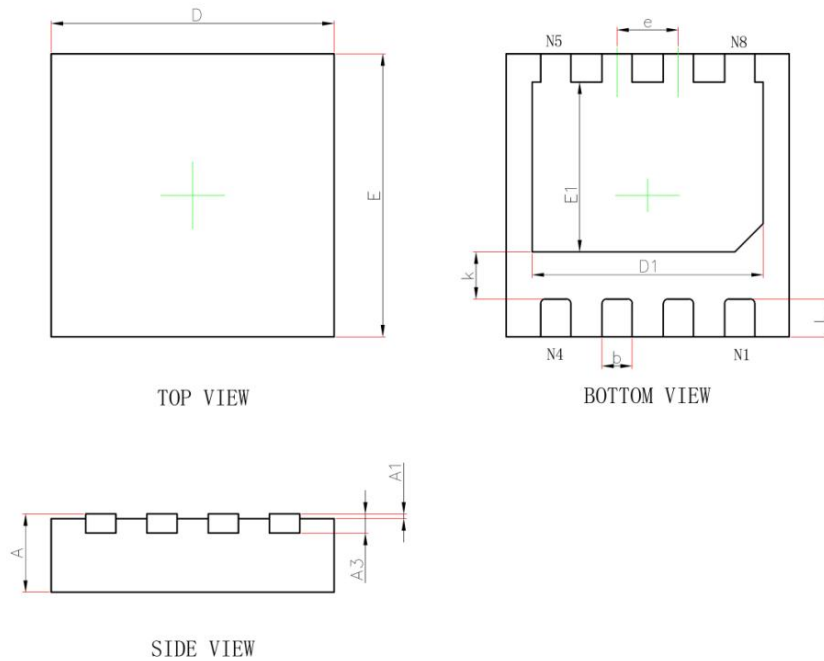
Typical Performance Characteristics
Figure 3: Transfer Characteristics

Figure 4: Output Characteristics

Figure 5: On-Resistance vs. Drain Current

Figure 6: On-Resistance vs. Gate Voltage


Figure 7: Body Diode Characteristics

Figure 8: Threshold Voltage


Mechanical Dimensions:
DFN3030-8L Package Information


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.700/0.800	0.800/0.900	0.028/0.031	0.031/0.035
A1	0.000	0.050	0.000	0.002
A3	0.203REF.		0.008REF.	
D	2.924	3.076	0.115	0.121
E	2.924	3.076	0.115	0.121
D1	2.350	2.550	0.093	0.100
E1	1.700	1.900	0.067	0.075
k	0.450	0.550	0.018	0.022
b	0.270	0.370	0.011	0.015
e	0.650TYP.		0.026TYP.	
L	0.324	0.476	0.013	0.019

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